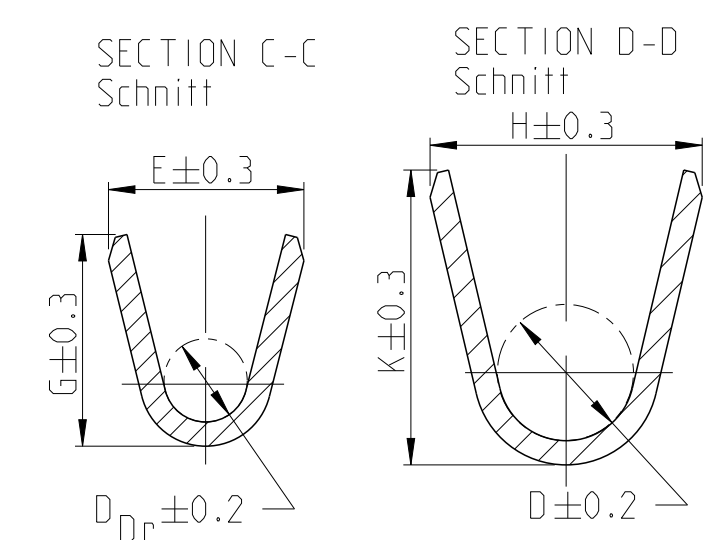
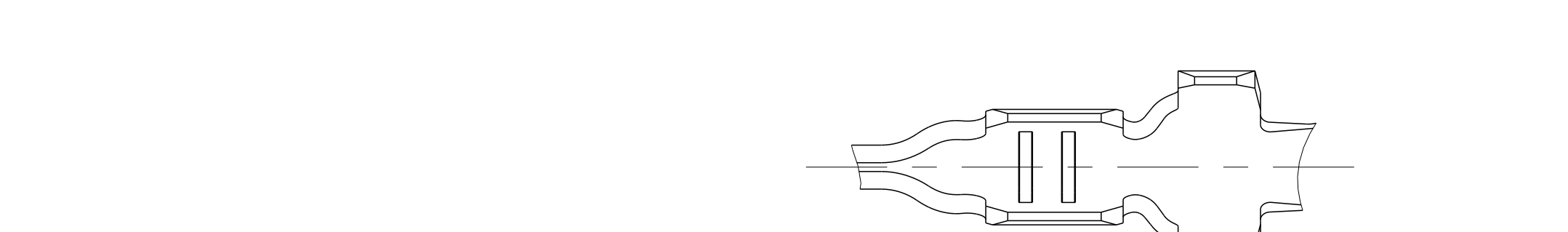
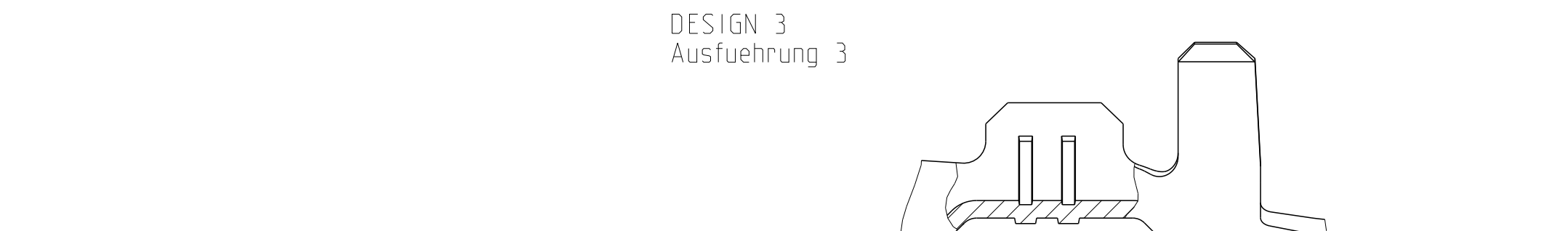
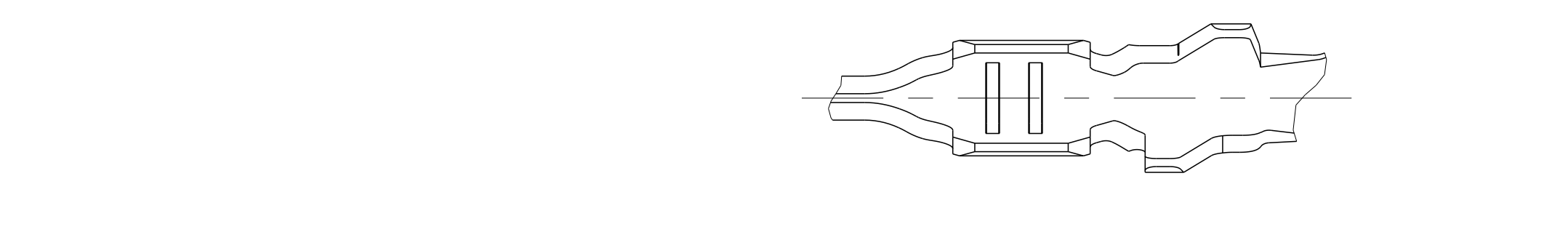
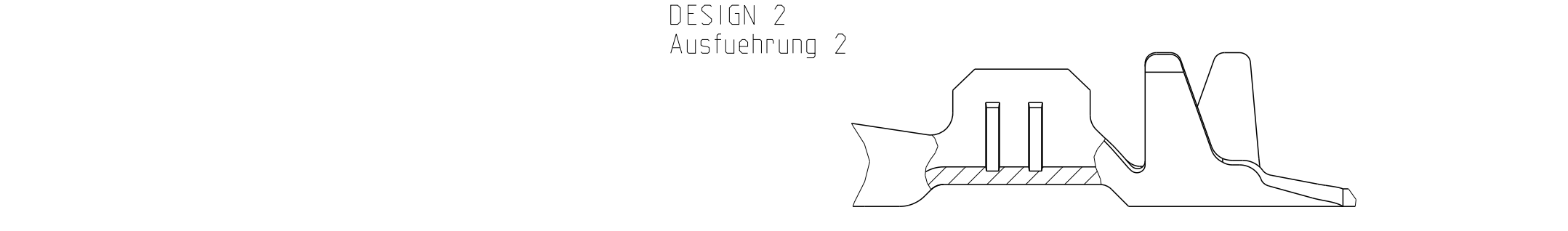
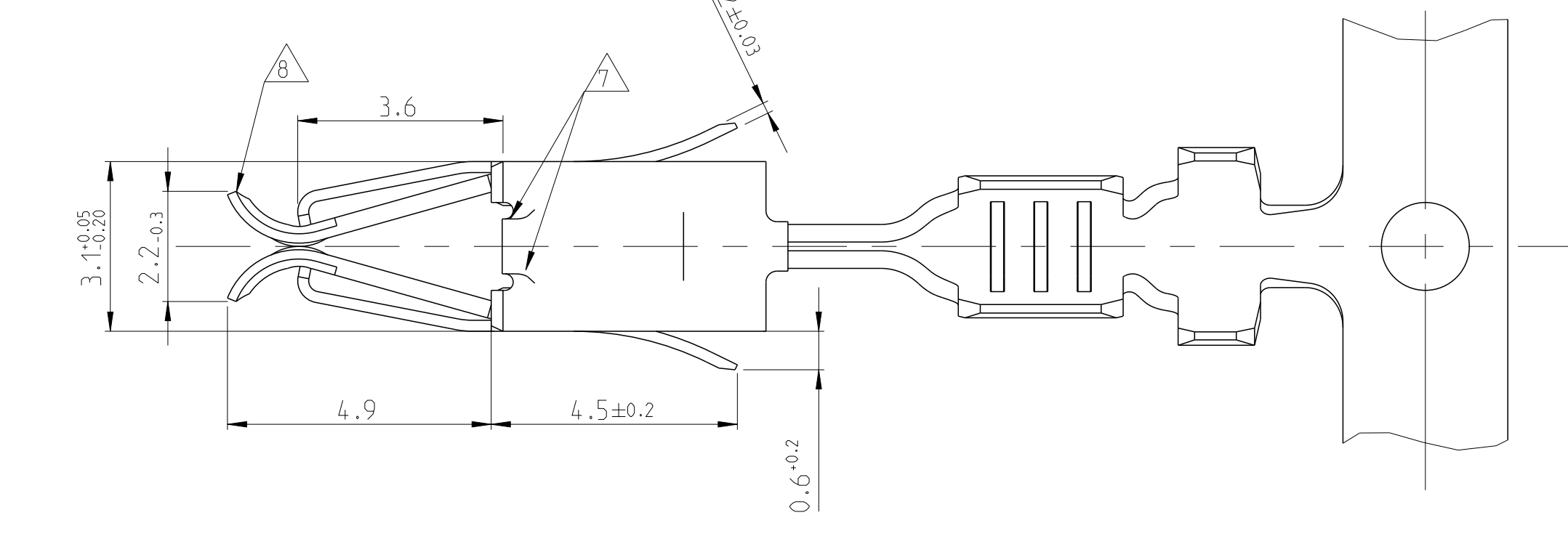
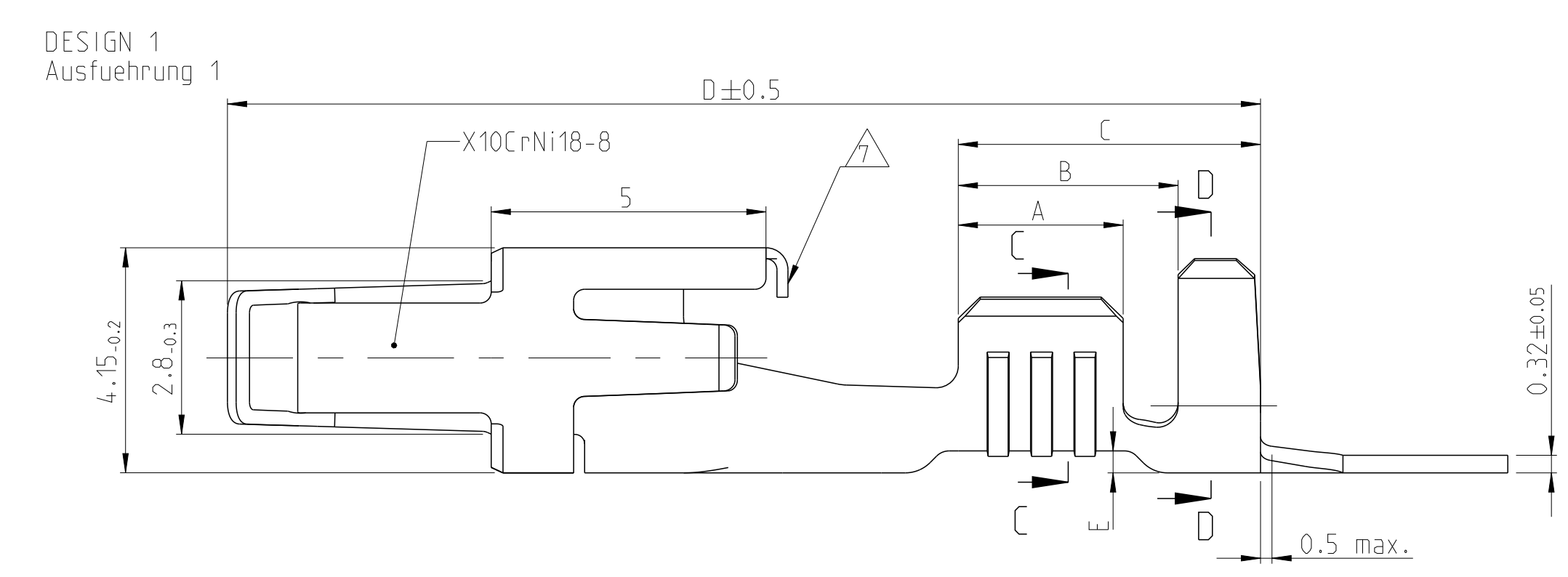


UNSEALED/ ungeölt
SINGLE WIRE SEAL/ Einzeldichtungssystem

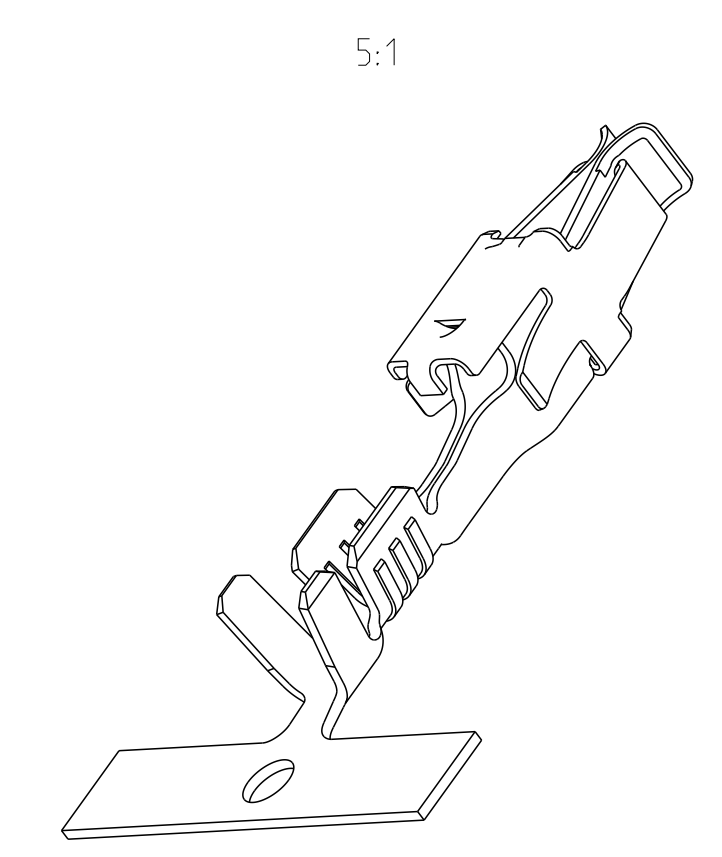
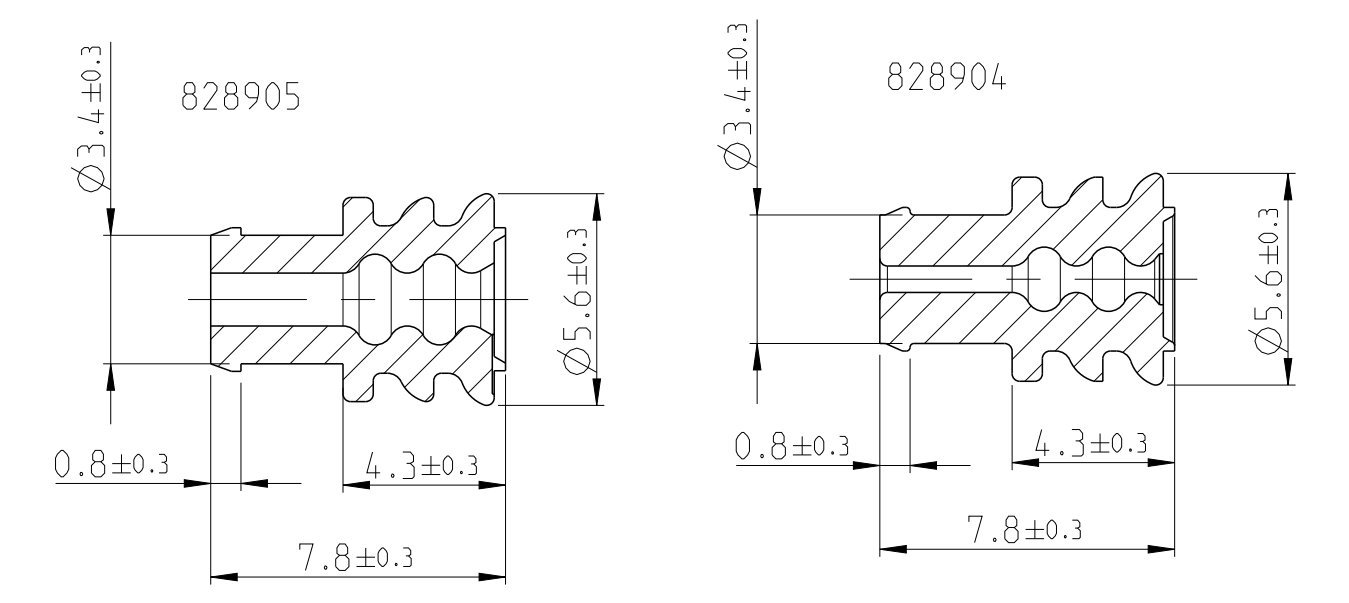


REV.	DESIGN Ausführung	MATERIAL Werkstoff	SURFACE Oberfläche	WIRE RANGE Drahtgrößenbereich [mm ²]	INSULATION Isolations Ø [mm]	STRIP FORM WIRE CRIMP Drahtcrimp-Bandware	INSUL.-CRIMP ISO-CRIMP Bandware	A	B	C	D	E
12	A	CuSn4	PRET INNED vorverzinkt min. 0.8 µm	0.5-1.0 FLR	1.4-2.3	E = 2.6 G = 2.8 DDr = 1.1	H = 3.6 K = 3.9 D = 1.8	3	4	5.5	18.8	0.4
12	A	CuSn4	PRET INNED vorverzinkt min. 0.8 µm	>1.0-2.5 FLR	2.1-3.1	E = 3.6 G = 3.8 DDr = 1.8	H = 4.7 K = 4.9 D = 2.6	3.3	4.3	5.8	18.8	0.4
	A	CuSn4	PLAIN BLANK	0.5-1.0 FLK	2.0-2.7	E = 2.6 G = 2.8 DDr = 1.1	H = 3.9 K = 4.1 D = 2.4	3	4	5.5	18.8	0.4
	M	CuNi12ZN24	PRET INNED vorverzinkt min. 0.8 µm									
	M	CuSn4	PRET INNED vorverzinkt min. 0.8 µm	0.5-1.0 FLK	2.0-2.7	E = 2.6 G = 2.8 DDr = 1.1	H = 3.9 K = 4.1 D = 2.4	3	4	5.5	18.8	0.4
	M	CuSn4	PRET INNED vorverzinkt min. 0.8 µm									
	M	CuFe2	PRET INNED vorverzinkt min. 0.8 µm									
15	A	CuFe2	PRET INNED vorverzinkt min. 1 µm	0.5-1.0 FLR	1.4-2.3	E = 2.6 G = 2.8 DDr = 1.1	H = 3.6 K = 3.9 D = 1.8	3.0	4.0	5.5	18.8	0.4
	A	CuSn4	PRET INNED vorverzinkt min. 1 µm	>1.0-2.5 FLR	2.1-3.1	E = 3.6 G = 3.8 DDr = 1.8	H = 4.7 K = 4.9 D = 2.6	3.3	4.3	5.8	18.8	0.4
	N	CuSn4	PRET INNED vorverzinkt min. 1 µm	>1.0-2.5 FLK	2.7-4.1	E = 3.6 G = 3.8 DDr = 1.8	H = 5.5 K = 5.8 D = 3.6	3.3	4.3	5.8	18.8	0.4
	N	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	R	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	R	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	P	CuSn4	PRET INNED vorverzinkt min. 1 µm	>1.0-2.5 FLR	2.1-3.1	E = 3.6 G = 3.8 DDr = 1.8	H = 4.7 K = 4.9 D = 2.6	3.3	4.3	5.8	18.8	0.4
	P	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	P	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	A	CuSn4	PLAIN BLANK	0.5-1.0 FLR	1.4-2.3	E = 2.6 G = 2.8 DDr = 1.1	H = 3.6 K = 3.9 D = 1.8	3	4	5.5	18.8	0.4
	N	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	N	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	N	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	M	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	M	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	M	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	C	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.2-0.5 FLR	1.0-1.6	E = 2.1 G = 2.1 DDr = 0.8	H = 2.7 K = 2.8 D = 1.4	2.5	3.5	5.6	18.8	0.4
	C	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	B	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	B	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	B	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	B	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	B	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.08-0.2 Sonderleitung	1.5-1.8	E = 1.7 G = 1.7 DDr = 0.6	H = 3.1 K = 3.2 D = 1.6	2.5	3.7	5.9	18.8	0.4
	A	CuSn4	PRET INNED vorverzinkt min. 0.8 µm	0.2-0.5 FLR	1.2-2.3	E = 2.1 G = 2.1 DDr = 0.8	H = 3.5 K = 3.6 D = 2.0	2.5	3.5	5	18.8	0.4
	D	CuFe2	PRET INNED vorverzinkt min. 0.8 µm									
	C	CuSn4	PRET INNED vorverzinkt min. 0.8 µm	0.2-0.5 FLK	1.2-2.3	E = 2.1 G = 2.1 DDr = 0.8	H = 3.5 K = 3.6 D = 2.0	2.5	3.5	5	18.8	0.4
	C	CuFe2	PRET INNED vorverzinkt min. 0.8 µm									
	A	CuSn4	PLAIN BLANK	0.2-0.5 FLR	1.15-1.6	E = 2.4 G = 2.3 DDr = 1	H = 2.9 K = 2.9 D = 1.4	2.5	3.5	5.6	18.8	0.2
	E	CuSn4	PRET INNED vorverzinkt min. 1 µm	>1.0-2.5 FLK	2.7-3.0	E = 3.6 G = 3.8 DDr = 1.8	H = 5.4 K = 4.6 D = 3.2	3.5	5.9	7.5	18.8	0.4
	E	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	D	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	D	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	E	CuSn4	PRET INNED vorverzinkt min. 1 µm	>1.0-2.5 FLR	2.7-3.0	E = 3.6 G = 3.8 DDr = 1.8	H = 5.4 K = 4.6 D = 3.2	3.5	5.9	7.5	21	0.4
	E	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	E	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.5-1.0 FLR	1.4-2.1	E = 2.6 G = 2.8 DDr = 1.1	H = 5.4 K = 4.6 D = 3.2	3	5.4	7	21	0.6
	E	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	G	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	G	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	F	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.5-1.0 FLR	1.4-2.1	E = 2.6 G = 2.8 DDr = 1.1	H = 5.4 K = 4.6 D = 3.2	3	5.4	7	18.8	0.6
	F	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	E	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.2-0.5 FLR	1.15-1.6	E = 2.1 G = 2.1 DDr = 0.8	H = 5.4 K = 4.6 D = 3.2	2.5	4.9	6.5	21	0.9
	E	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	D	CuSn4	PRET INNED vorverzinkt min. 1 µm									
	D	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	D	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.2-0.5 FLR	1.15-1.6	E = 2.1 G = 2.1 DDr = 0.8	H = 5.4 K = 4.6 D = 3.2	2.5	4.9	6.5	18.8	0.9
	D	CuFe2	PRET INNED vorverzinkt min. 1 µm									
	C	CuSn4	PRET INNED vorverzinkt min. 1 µm	0.2-0.5 FLR	1.15-1.6	E = 2.1 G = 2.1 DDr = 0.8	H = 5.4 K = 4.6 D = 3.2	2.5	4.9	6.5	18.8	0.9
	C	CuFe2	PRET INNED vorverzinkt min. 1 µm									

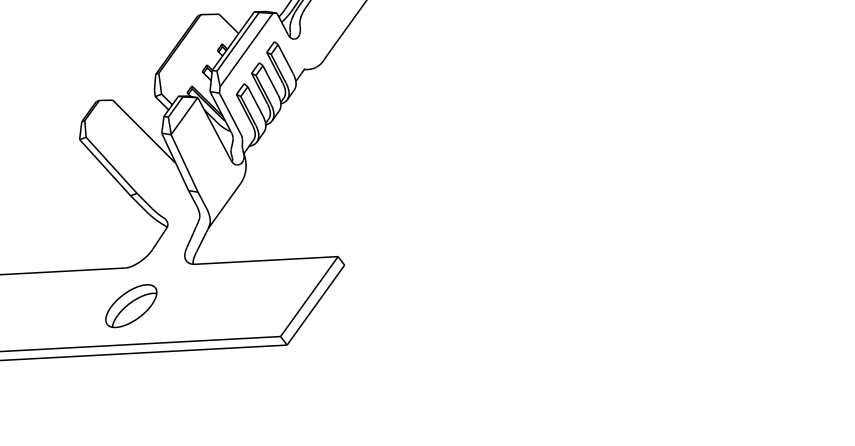
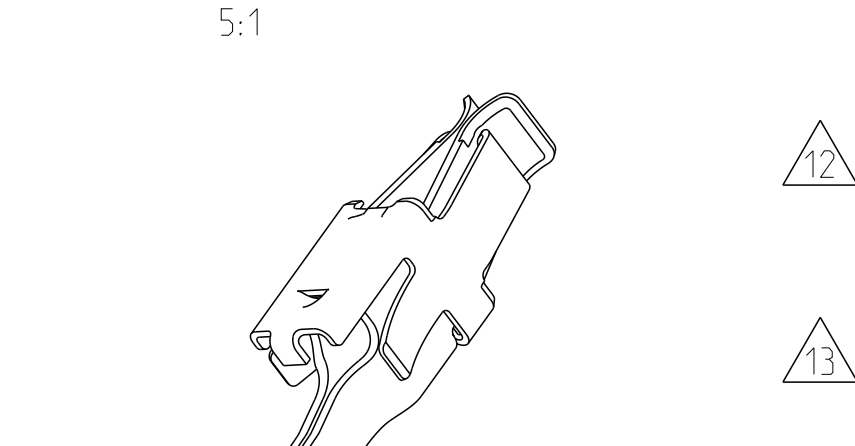
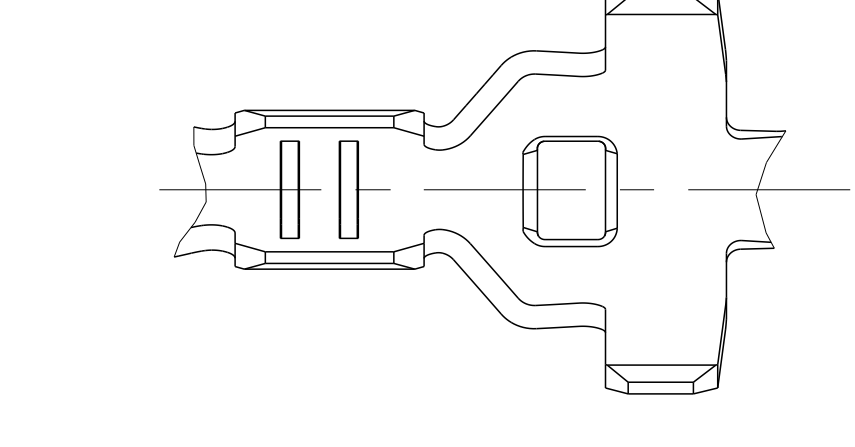
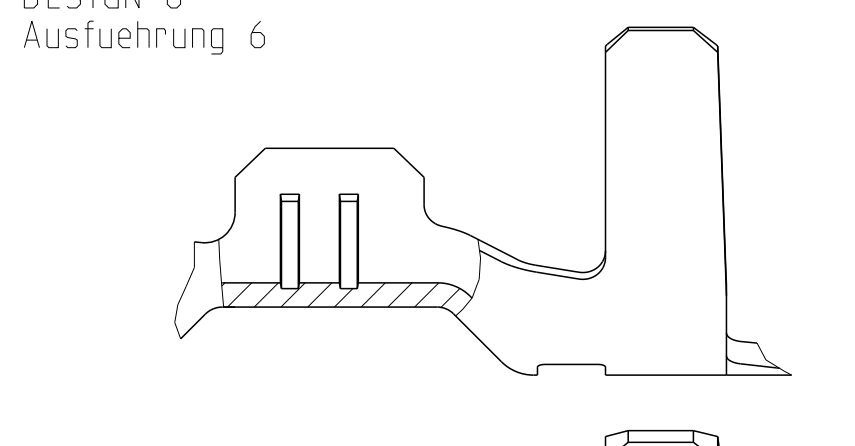
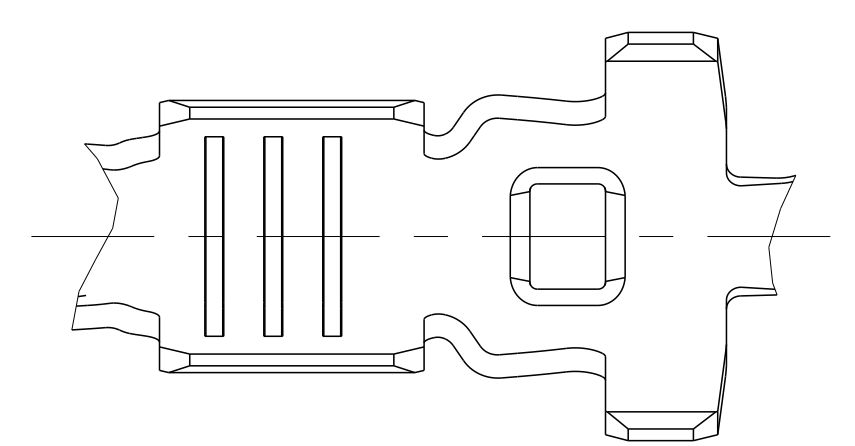
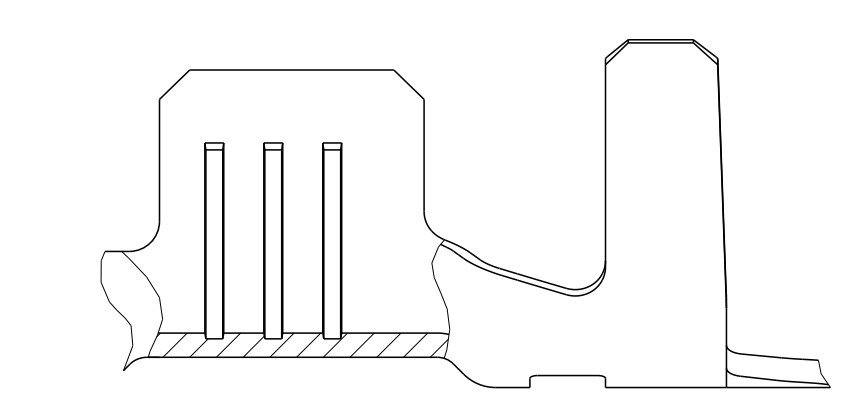
SEE APPLICATION - SPECIFICATION
siehe Verarbeitungspezifikation
114-18050



ORDER No. Bestell-Nr.	INSULATION Isolations Ø	COLOUR Farbe
828904-1	1.2-2.1	blue blau
828905-1	2.2-3.0	white weiss



DESIGN 5 Ausfuehrung 5



NOTES
Bemerkungen

- 1 CONTACT BODY PRE-SILVER PLATED MIN. 0.8 µm
Kontaktkoerper vorversilbert min. 0.8 µm
- 2 CONTACT ZONE SELECTIVE PRE-SILVER PLATED MIN. 3 µm
Kontaktzone selektiv vorversilbert min. 3 µm
- 3 CONTACT ZONE GOLD PLATED MIN. 0.8 µm OVER MIN. 1.3 µm NICKEL-LAYER
Kontaktzone vergoldet min. 0.8 µm ueber min. 1.3 µm Nickel-Zwischenschicht
- 4 CRIMP AREA MIN. 1 µm TIN PLATED OVER NICKEL-LAYER
Crimbereich min. 1 µm verzinkt ueber Nickel-Zwischenschicht
- 5 CANTILEVER SPRING INSIDE AND OUTSIDE 0.4-1.2 µm GOLD PLATED
Ueberfeder innen und aussen 0.4-1.2 µm vergoldet
- 6 CONTACT BODY, CONTACT SPRING INSIDE AND CRIMP AREA MIN. 1 µm TIN PLATED OVER NICKEL-LAYER.
TOUCHING AREA TO CANTILEVER SPRING AND CONTACT SPRING OUTSIDE
SELECTIVE 0.8 µm GOLD OVER MIN. 1.3 µm NICKEL-LAYER
Kontaktkoerper, Kontaktfeder innen und Crimbereich min. 1.3 µm verzinkt ueber Nickel-Zwischenschicht, Anlagelaechse zur Ueberfeder und Kontaktfeder aussen selektiv 0.8 µm vergoldet ueber min. 1 µm Nickel-Zwischenschicht
- 7 CONTACT ZONE AND TOUCHING AREA TO CANTILEVER SPRING MIN. 0.8 µm SELECTIVE GOLD PLATED OVER 1.3 µm NICKEL PLATED. CRIMP AREA MIN. 1 µm TIN PLATED OVER NICKEL-LAYER
Kontaktzone und Anlagelaechse zur Ueberfeder min. 0.8 µm vergoldet ueber min. 1.3 µm Nickel-Zwischenschicht Crimbereich min. 1 µm verzinkt ueber Nickel-Zwischenschicht
- 8 CONTACT BODY AND CRIMP AREA MIN. 1 µm TIN PLATED OVER NICKEL-LAYER.
TOUCHING AREA TO CANTILEVER SPRING SELECTIVE 0.8 µm GOLD OVER MIN. 1.3 µm NICKEL-LAYER
Kontaktkoerper und Crimbereich min. 1 µm verzinkt ueber Nickel-Zwischenschicht, Anlagelaechse zur Ueberfeder selektiv 0.8 µm vergoldet ueber min. 1.3 µm Nickel-Zwischenschicht
- 9 CONTACT OFF OPTIONAL
Abschnitt/Freisschnitt optional
- 10 SAWAG ONLY FOR PN 929937, 929939, 929941
Swage nur fuer PN 929937, 929939, 929941
- 11 VARIANTS WITH GAP-SIZE 0.3mm (±0.1)
Varianten mit Gap-Size 0.3mm (±0.1)
- 12 CONTACTS DIPPED IN OR SPRAYED WITH LUBRICANT BARRIERTA
Kontakte getaucht oder besprueht mit Lubricant Barrierta
- 13 ACCORDING INSULATION DIA IS TO CHOOSE THE SINGLE WIRE SEAL
Entsprechend dem Isolationsdurchmesser ist die Einzel-Dichtung auszuwaehlen
- 14 VARIANTS WITH GAP-SIZE 0.65mm (-0.1)
Varianten mit Gap-Size 0.65mm (-0.1)
- 15 VARIANTS WITH GAP-SIZE 0.15mm (-0.05)
Varianten mit Gap-Size 0.15mm (-0.05)

DIMENSIONS: (mm)		DATE: 09JUN09	APPD: Hqs	PRODUCT SPEC: 108-18013	APPLICATIVE SPEC: 114-18050	SCALE: 1:1	SHEET: 1 OF 1	REV: A16
MATERIAL: SEE TABLE		Customer Drawing		PRODUCT GROUP DRAWING FOR JUNIOR POWER TIMER CONTACT Produkt-Gruppen-Zeichnung fuer JPT		PREPARED BY: A 00779 ©=1355046		

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[2-929939-1 \(Mouser Reel\)](#) [2-929939-1 \(Cut Strip\)](#)